



# SRAM to DDR Component

## Download

Reference Component ([https://reference.digilentinc.com/\\_media/nexys4-ddr/ram2ddr\\_refcomp.zip](https://reference.digilentinc.com/_media/nexys4-ddr/ram2ddr_refcomp.zip)) UCF file for pinout ([https://reference.digilentinc.com/\\_media/nexys4-ddr/nexys4ddrmemorypinout.zip](https://reference.digilentinc.com/_media/nexys4-ddr/nexys4ddrmemorypinout.zip))

## Description


**Note: There is a problem mapping the MIG in ISE. In short, the tools do not see the MIG generated UCF file. This issue can be solved by following the flow found  here. (<http://www.xilinx.com/support/answers/36427.html>) The diligent support thread associated with this issue is  here. (<https://forum.digilentinc.com/topic/1469-map-problem-on-nexys4ddr/>)**

This component implements a simple asynchronous SRAM interface to DDR2 converter for the Digilent Nexys4-DDR board. It uses the industry-standard SRAM control bus. Read operations are initiated by bringing CEN, OEN and LB/UB low while keeping WEN high. Valid data will be driven out the Data Output port after the specified access time has elapsed. Write operations occur when CEN, WEN and LB/UB are driven low while keeping OEN high.

The LB enable and UB enable signals support byte-wide (8-bit) data writes. During write operations, any disabled bytes will be masked out and not transmitted to the DDR. When both the LB and UB are enabled than word-wide (16-bit) data writes are executed.

This component is particularly useful for those who would like to port a design that targeted an earlier Nexys model and asynchronously accessed the onboard CellRAM. This component shares the same interface, and should allow the previous project to continue to work on the Nexys4-DDR. The only change that must be made is to the read cycle and write cycle wait times. They have increased to 210 and 260 ns, respectively

The converter component instantiates a LogiCORE MIG (Memory Interface Generator) that is configured with the following settings:

Parameter	Value
Controller Type	DDR2 SDRAM
Clock Period	3333 ps (300 MHz  )
PHY to Controller Clock Ratio	2:1
Memory Type	Components
Memory Part	MT47H64M16HR-25E
Data Width	16
Data Mask	Enabled
Ordering	Strict
Input Clock Period	5000 ps (200MHz)
Burst Type	Sequential
Output Drive Strength	Fullstrength
Controller Chip Select Pin	Enable
RTT (nominal) – ODT	50 Ohms
Memory Address Mapping Selection	Bank-Row-Column

Parameter	Value
System Clock	No Buffer
Reference Clock	Use System Clock
System Reset Polarity	Active Low
Debug Signals for Memory Controller	Off
Internal Vref	Enabled
IO Power Reduction	On
XADC Instantiation	Enabled <sup>1</sup>
Internal Termination Impedance	50 Ohms

Table 1. MIG settings

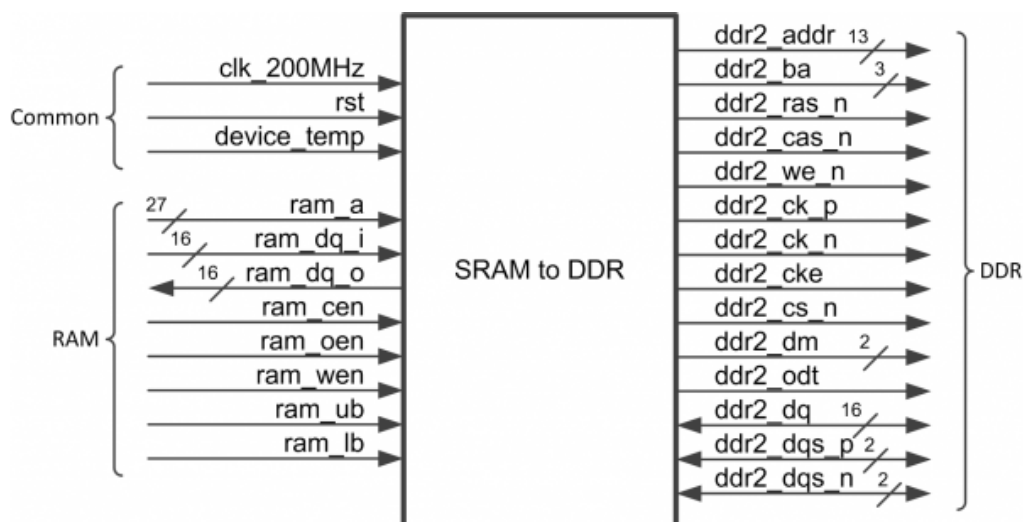
<sup>1</sup>If the XADC is used elsewhere in the design, this should be disabled. It is disabled in the Ram2Ddr version of this core

This project contains two different components: Ram2Ddr and Ram2DdrXadc. If your design does not use the XADC core anywhere else, you should use the Ram2DdrXadc component. It automatically instantiates the XADC internally to monitor the chip temperature. If your design does use the XADC core, you should use the Ram2Ddr component. You will then have to connect the device\_temp line of the Ram2Ddr component to the XADC component, as described on page 122 in version 1.9 of Xilinx's [7 Series FPGAs Memory Interface Solutions Guide \(UG586\)](http://www.xilinx.com/support/documentation/ip_documentation/mig_7series/v1_9/ug586_7Series_MIS.pdf) ([http://www.xilinx.com/support/documentation/ip\\_documentation/mig\\_7series/v1\\_9/ug586\\_7Series\\_MIS.pdf](http://www.xilinx.com/support/documentation/ip_documentation/mig_7series/v1_9/ug586_7Series_MIS.pdf)).

Components can either be inserted into a project as a pre-compiled netlist (.ngc), or as sources by copying the VHDL and MIG project files into your project. Both are included with the download.

## Port Descriptions

Figure 1 shows the ram2ddr component block diagram with its ports:



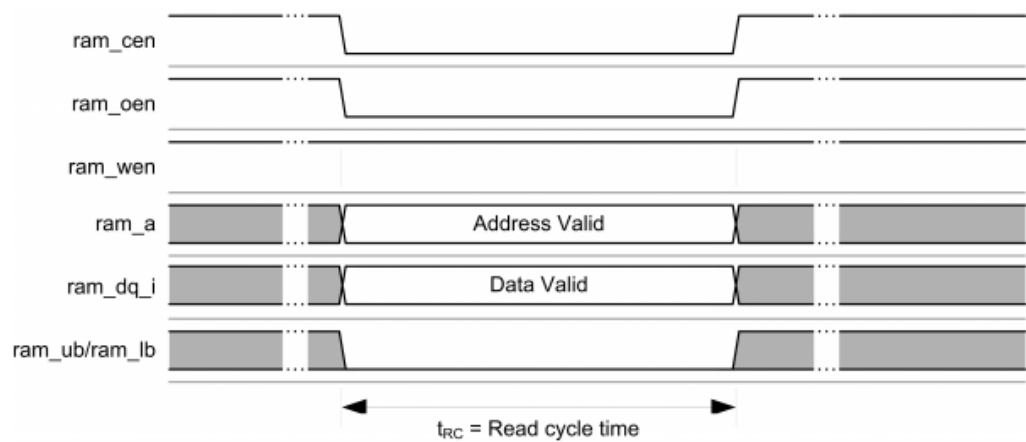
([https://reference.digilentinc.com/\\_media/nexys4-ddr/ram2ddr\\_fig1.png](https://reference.digilentinc.com/_media/nexys4-ddr/ram2ddr_fig1.png)) Figure 1. Block Diagram

Port	Direction	Description
clk_200MHz	Input	Single-ended, buffered 200 MHz clock input
rst	Input	Active-high global reset

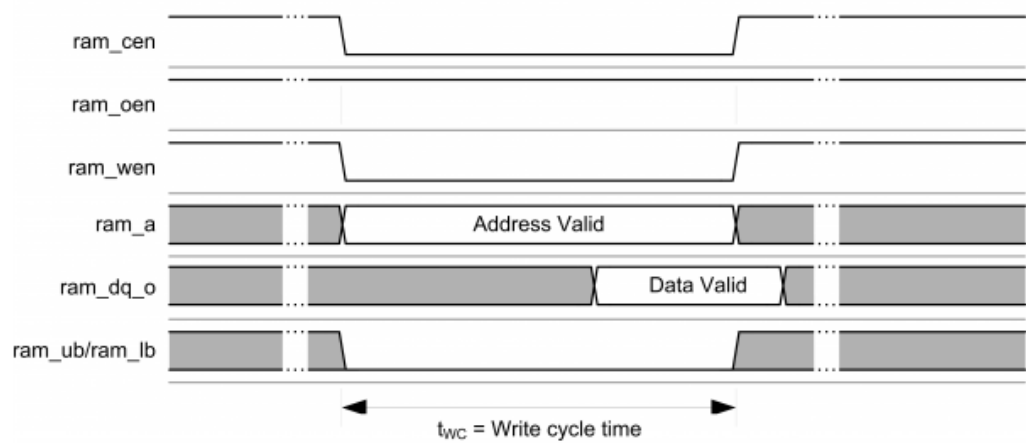
Port	Direction	Description
device_temp	Input	This port is active only in the ram2ddr.ngc file (where the XADC module is not internally instantiated) and shall be tied to <u>GND()</u> in the ram2ddrxadc.ngc component. See “Xilinx UG586 7 Series FPGAs Memory Interface Solutions” for more details on driving this port.
<b><u>RAM()</u></b>		
ram_a (26:0)	Input	Input address
ram_dq_i (15:0)	Input	Data input
ram_dq_o (15:0)	Output	Data output
ram_cen	Input	Active-low Chip Enable
ram_oen	Input	Active-low Output Enable
ram_wen	Input	Active-low Write Enable
ram_ub	Input	Active-low Upper Byte select
ram_lb	Input	Active-low Lower Byte select
<b>DDR</b>		
ddr2_addr (12:0)	Output	Memory Address output
ddr2_ba (2:0)	Output	Bank Address
ddr2_ras_n	Output	Active-low Row Address Strobe
ddr2_cas_n	Output	Active-low Column Address Strobe
ddr2_we_n	Output	Active-low Write Enable
ddr2_ck_p, ddr2_ck_n	Output	Differential Memory Clock output
ddr2_cke	Output	Active-high Memory Clock Enable
ddr2_cs_n	Output	Active-low Chip Select
ddr2_dm (1:0)	Output	Output Data Mask
ddr2_odt	Output	On-Die Termination
ddr2_dq (15:0)	Bidirectional	Data input/output bus
ddr2_dqs_p (1:0), ddr2_dqs_n (1:0)	Bidirectional	

Table 2. Port Descriptions

## Bus Timing



([https://reference.digilentinc.com/\\_media/nexys4-ddr/ram2ddr\\_fig2.png](https://reference.digilentinc.com/_media/nexys4-ddr/ram2ddr_fig2.png)) Figure 2. Read Operation



([https://reference.digilentinc.com/\\_media/nexys4-ddr/ram2ddr\\_fig3.png](https://reference.digilentinc.com/_media/nexys4-ddr/ram2ddr_fig3.png)) Figure 3. Write Operation

Parameter	Symbol	Min	Max	Unit
Read cycle time	tRC	210	-	ns
Write cycle time	tWR	260	-	ns

### Usage with Other Boards

In order to use this reference component with boards other than the Digilent Nexys4-DDR, the following should be modified:


- Memory Interface Generator must be rerun and the following must be changed:
  - Controller Type and/or Memory Part (depending on the memory)
  - Controller Chip Select Pin (depending on the board)
  - RTT (nominal) – On Die Termination (depending on the board)
  - Internal Vref (depending on the board)
  - Internal Termination Impedance (depending on the board).
  - Pin constraints must be changed to match how the DDR2 is connected on the new board
- Update the instantiation of the MIG component according to the new settings


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